

Appli-Thane® 7800

0.3 W/mK

This thixotropic, easily reworkable aerospace urethane is ideal for bonding and staking applications where thermal conductivity isn't required. Appli-Thane®7800 was designed specifically to have a 3-4 times longer pot life, half the cure time, and four times longer shelf life than standard aerospace urethanes. The material features a room temperature cure while also meeting NASA's low outgassing requirements. With low modulus and low Tg, 7800 is a suitable substitute for many silicones in electronic applications.

UNCURED	
Work Life @ 25°C	1.5 hours
Viscosity @ 25°C	45,000 cPs
Thixotropic Index	3.0
Shelf Life @ -40°C	6 Months
	9 Months
Shelf Life @ -60°C CURE OPTIONS	7.10
CURED PROPERTIES	2.5 hours @ 66°C 7 days @ 25°C Based on cure of 2.5 hours @ 66°C
Color	Translucent
Shore A Hardness	65
Glass Transition Temp (°C)	-74
Density (g/cc)	1.0
Lap Shear 2024T3 Clad (psi)	500
	625
Tensile Strength (psi)	
Tensile Modulus (psi)	400
Elongation (%)	90
Fungus Resistance	Non-nutrient
Chloride Ion Concentration, ppm	26.7
ELECTRICAL PROPERTIES	Based on cure of 2.5 hours @ 66°C
Dielectric Constant	3.5 @ 10 kHz 3.1 @ 100 kHz 2.9 @ 1 MHz
Dissipation Factor	0.08 @ 10 kHz
Dielectric Strength (volts/mil)	1,220 (thickness=0.02")
Volume Resistivity (ohm-cm)	2.2E 13 @ 500 VDC
THERMAL PROPERTIES	Based on cure of 2.5 hours @ 66°C
CTE below Tg (ppm/°C)	80
CTE above Tg (ppm/°C)	200
Glass Transition Temp (°C)	-74
Operating Temp. Range (°C)	-100 to 125
Thermal Conductivity (W/mK)	0.3
sed on cure of 2.5 hours @ 66°C	

Thixotropic Electrically Insulative Flexible Hydrolytic Stability Long Pot Life Low Glass Transition Temperature Low Modulus Meets NASA Outgassing Requirements Solvent Resistant Fungus Resistant	KEY FEATURES	
Flexible Hydrolytic Stability Long Pot Life Low Glass Transition Temperature Low Modulus Meets NASA Outgassing Requirements Solvent Resistant	Thixotropic	
Hydrolytic Stability Long Pot Life Low Glass Transition Temperature Low Modulus Meets NASA Outgassing Requirements Solvent Resistant	Electrically Insulative	
Long Pot Life Low Glass Transition Temperature Low Modulus Meets NASA Outgassing Requirements Solvent Resistant	Flexible	
Low Glass Transition Temperature Low Modulus Meets NASA Outgassing Requirements Solvent Resistant	Hydrolytic Stability	
Low Modulus Meets NASA Outgassing Requirements Solvent Resistant	Long Pot Life	
Meets NASA Outgassing Requirements Solvent Resistant	Low Glass Transition Temperature	
Solvent Resistant	Low Modulus	
	Meets NASA Outgassing Requireme	ents
Fungus Resistant	Solvent Resistant	
	Fungus Resistant	

Chat with a specialist:

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OUTGASSING PROPERTIES	
TML (%)	0.43
CVCM (%)	0.01
WVR (%)	0.17
ACOUSTIC PROPERTIES	
Velocity (m/s)	1,616
Impedance (MRayls)	1.60
Loss (dB/cm-MHz)	-6.9
Density (g/cc)	1.0